MERHEIN
Technical Datasheet

15 April 2026

Wafer Thinning System for Semiconductor Manufacturing

This advanced wafer thinning system is designed for precision semiconductor manufacturing. It utilizes state-of-the-art technology to achieve uniform and controlled material removal, ensuring optimal wafer flatness and thickness.

Overview

Precision Thinning Capability

This advanced wafer thinning system is engineered for high-precision semiconductor manufacturing, delivering uniform material removal across diverse wafer sizes and materials. The equipment integrates automated handling and real-time process monitoring to ensure superior flatness, optimized thickness, and consistent high yields. Designed for efficiency and safety, it features a intuitive user interface and robust interlock systems to support seamless high-throughput operations.

Technical Capabilities

Operational Features

- Automated wafer handling
- Real-time process monitoring
- Precision material removal
- Comprehensive safety interlocks

System Performance Metrics

1 High	1 Automated
Throughput Level	Operation Mode

Compliance and Standards

Certifications	Industrial Grade, Safety Certified

Rooms 05–15, 13A/F South Tower, World Finance Centre, Harbour City, 17 Canton Rd, Tsim Sha Tsui, Kowloon, Hong Kong